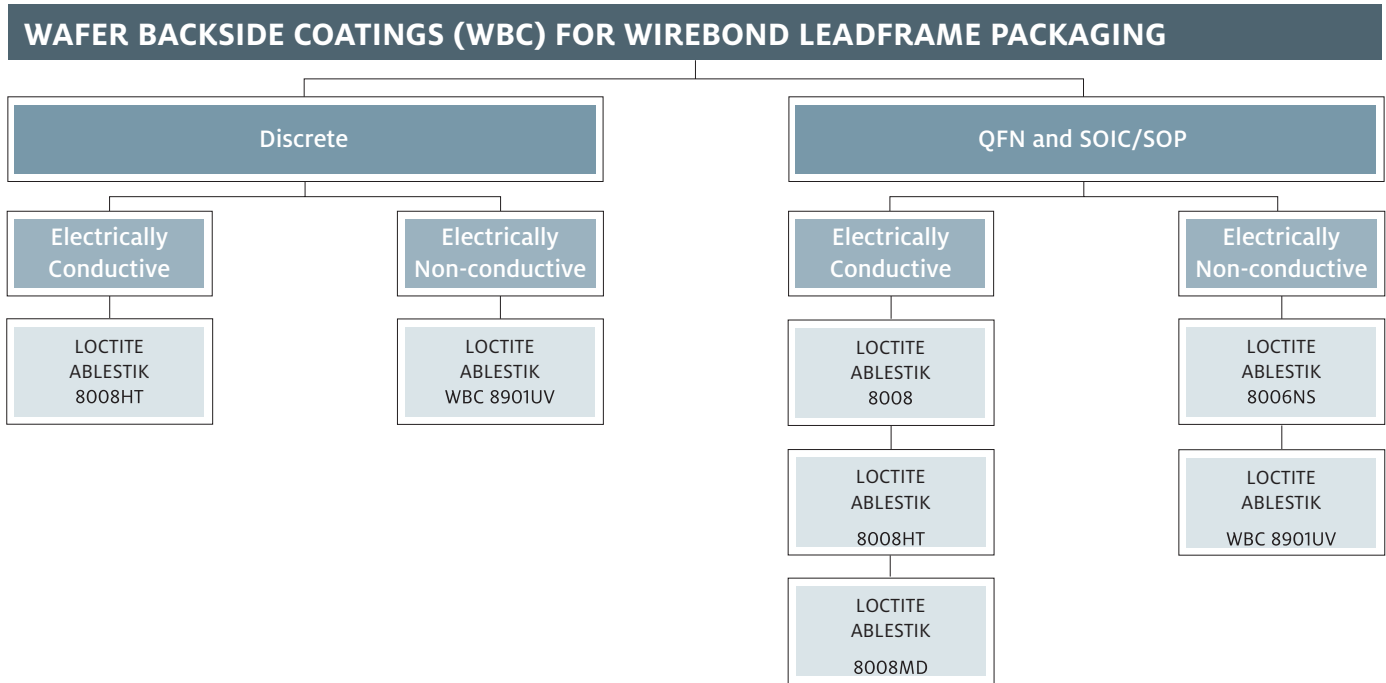




Henkel Solutions for Leadframe Packaging Wafer Backside Coatings



ELECTRICALLY CONDUCTIVE WAFER BACKSIDE COATINGS (WBC)

PRODUCT	DESCRIPTION	KEY ATTRIBUTES	DIE SIZE (mm)	SUBSTRATE FINISH	MOISTURE SENSITIVITY LEVEL, MSL	VOLUME RESISTIVITY (Ohm·cm)	THERMAL CONDUCTIVITY (W/m·K)	RECOMMENDED CURE
LOCTITE ABLESTIK 8008	Ag-filled die attach wafer backside coating adhesive	<ul style="list-style-type: none"> Excellent stencil printing and low surface roughness Void-free bondline without bleed Oven B-stage and snap or oven cure 	≤ 3 x 3	Cu, Ag or PPF	L1 260°C capable	1.0 x 10 ⁻⁴	2.2	60 sec. at 230°C (snap)
LOCTITE ABLESTIK 8008HT	Ag-filled die attach wafer backside coating adhesive	<ul style="list-style-type: none"> Applied by stencil printing Void-free bondline without bleed Oven B-stage and snap or oven cure 	≤ 1 x 1	Cu, Ag or PPF	L1 260°C capable	6.0 x 10 ⁻⁵	11.0	20 sec. at 170°C (snap)
LOCTITE ABLESTIK 8008MD	Ag-filled die attach wafer backside coating adhesive	<ul style="list-style-type: none"> Applied by stencil printing Low stress Good substrate wetting Oven B-stage and oven cure 	≤ 4 x 4	Cu, Ag or PPF	L1 260°C capable	5.0 x 10 ⁻⁴	6.0	10 min. ramp and 60 min. hold at 115°C

ELECTRICALLY NON-CONDUCTIVE WAFER BACKSIDE COATINGS (WBC)

PRODUCT	DESCRIPTION	KEY ATTRIBUTES	DIE SIZE (mm)	SUBSTRATE FINISH	MOISTURE SENSITIVITY LEVEL, MSL	MODULUS AT 25°C (MPa)	CTE (ppm/°C)		RECOMMENDED CURE
							Below T _g	Above T _g	
LOCTITE ABLESTIK 8006NS	Alumina/silica-filled, epoxy die attach wafer backside coating adhesive	<ul style="list-style-type: none"> Applied by stencil or screen printing Consistent bondline down to 25 µm with minimal die tilt Oven B-stage and oven cure 	≤ 4 x 4	Cu, Ag or PPF	L1 260°C capable	4,376	33	136	2 hr. at 160°C
LOCTITE ABLESTIK WBC 8901UV	Die attach wafer backside coating adhesive	<ul style="list-style-type: none"> Wide process windows 5 to 60 µm bondline control Low viscosity before B-stage Can be spray coated on Dicing Before Grinding (DBG) wafers UV B-stage and oven cure 	≤ 1 x 1	Cu, Ag or PPF	L2 260°C capable	3,585	45	142	15 min. ramp and 30 min. hold at 90°C + 4 min. ramp and 45 min. hold at 120°C

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